

Alpha & Omega Semiconductor Product Reliability qualification Report

AOK30B135C1, rev A

Plastic Encapsulated Device

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This AOS product reliability report summarizes the qualification result for AOK30B135C1. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOK30B135C1 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

I. Reliability Stress Test Summary and Results

Test Item	Test Condition	Time Point	Total Sample Size	Number of Failures	Reference Standard
HTGB	Temp = 175°C , Vge=100% of Vgemax	1000 hrs	231 pcs	0	JESD22-A108
HTRB	Temp = 175°C , Vce=80% of Vcemax	1000 hrs	231 pcs	0	JESD22-A108
HAST	130°C , 85%RH, 33.3 psia, Vce = 80% of Vcemax up to 42V	96 hrs	231 pcs	0	JESD22-A110
H3TRB	85°C , 85%RH, Vce = 80% of Vcemax up to 100V	1000 hrs	231 pcs	0	JESD22-A101
Autoclave	121°C , 29.7psia, RH=100%	96 hrs	231 pcs	0	JESD22-A102
Temperature Cycle	-65°C to 150°C , air to air,	1000 cycles	231 pcs	0	JESD22-A104
IOL	Δ Tj = 100°C	6000 cycles	231 pcs	0	MIL-STD-750 Method 1037

Note: The reliability data presents total of available generic data up to the published date.

II. Reliability Evaluation

FIT rate (per billion): 2.61

MTTF =43670 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate = $Chi^2 \times 10^9$ [2 (N) (H) (Af)] = 2.61 MTTF = 10^9 / FIT = 43670 years

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from burn-in tests

H = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [Af] = Exp [Ea / k (1/Tj u - 1/Tj s)]

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	125 deg C	150 deg C	175 deg C
Af	758	256	95	38	9.7	2.9	1

Ti s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, 8.617164 X 10⁻⁵eV / K